

15.7

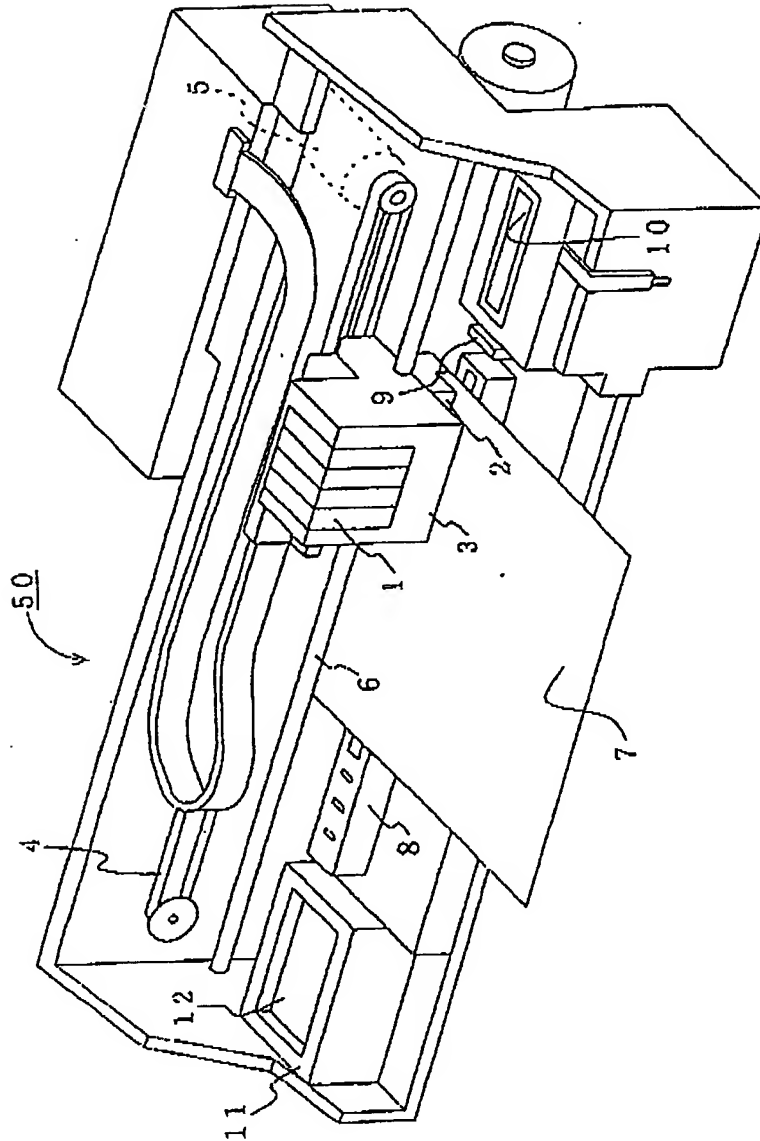
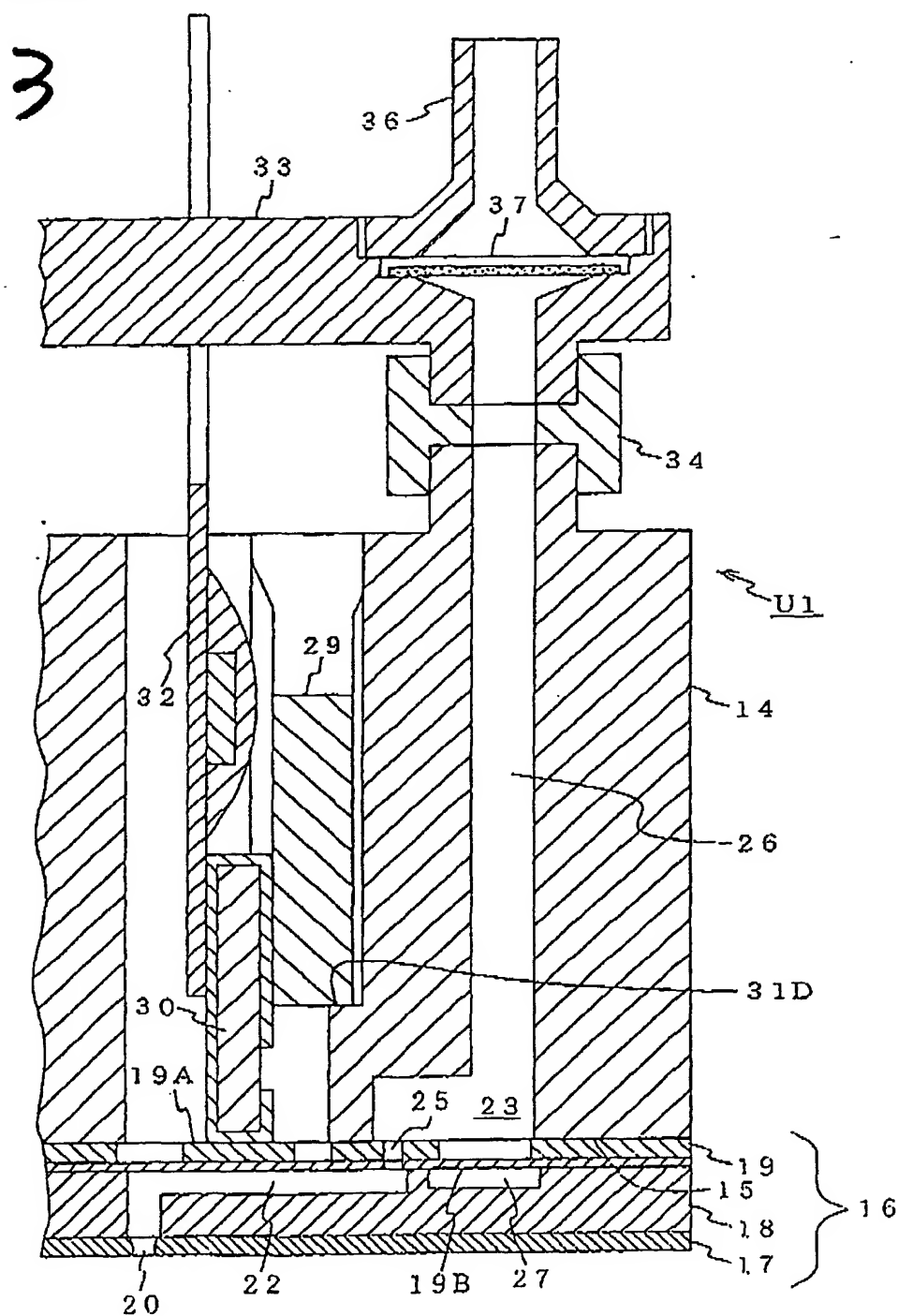
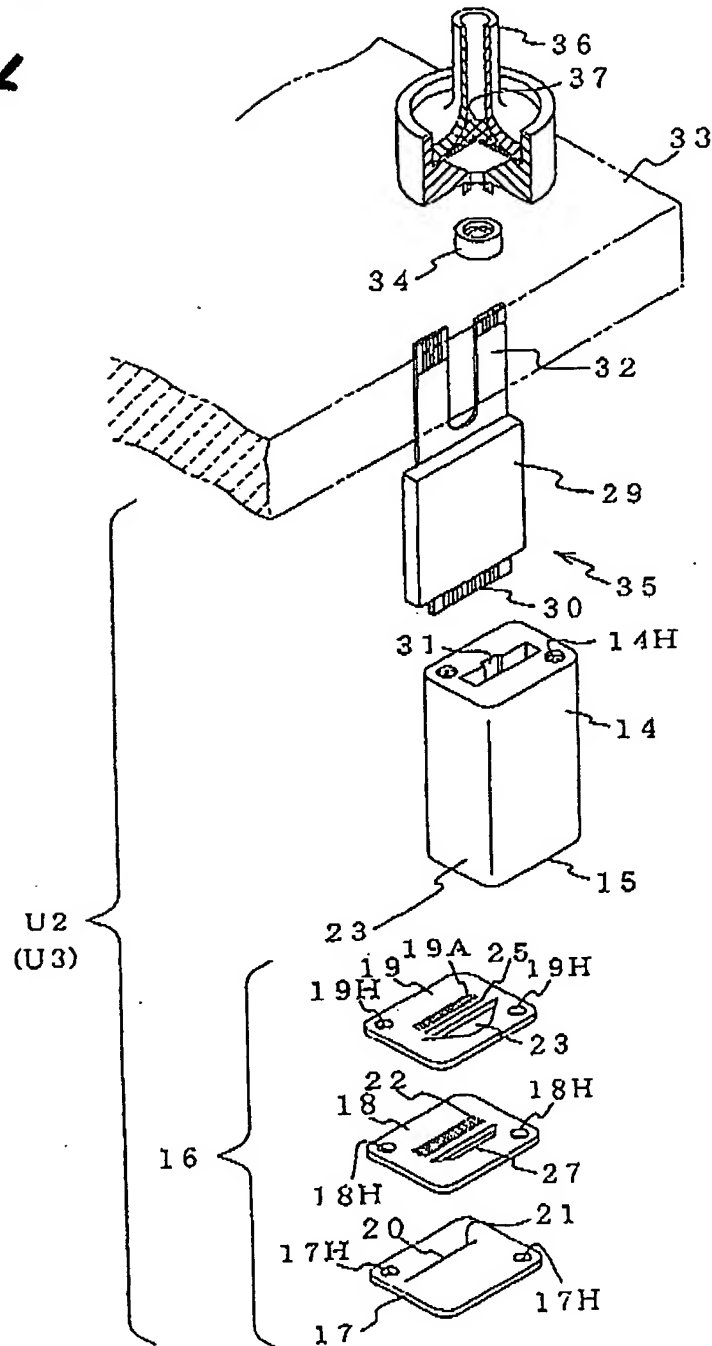




FIG. 3



【圖 2】





~~FIG. 6~~ FIG. 6A

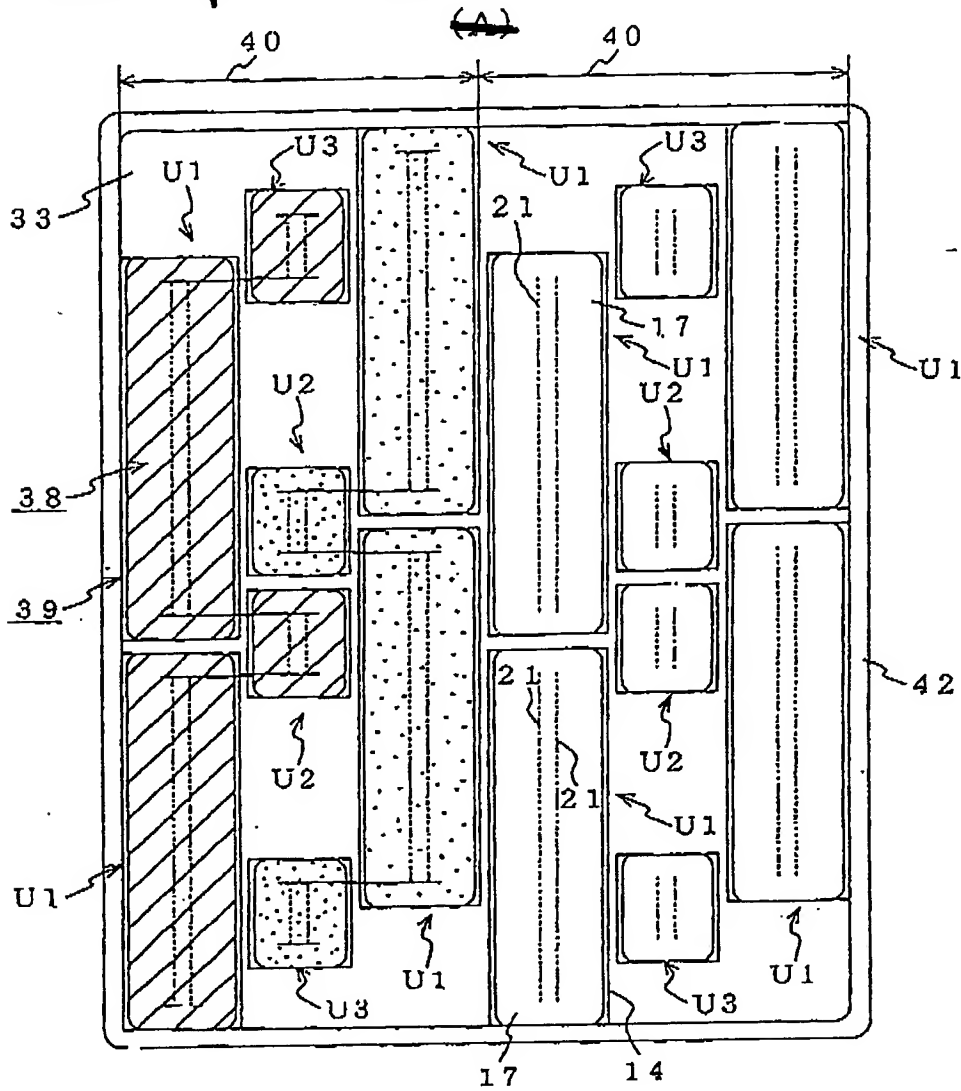
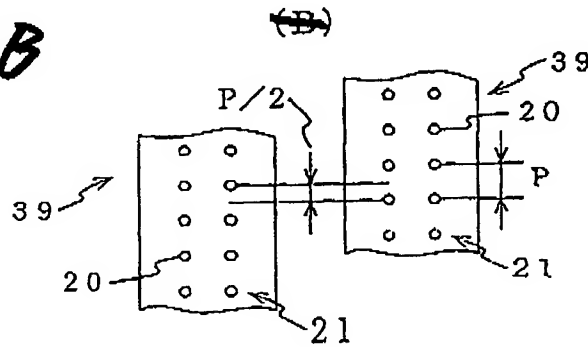
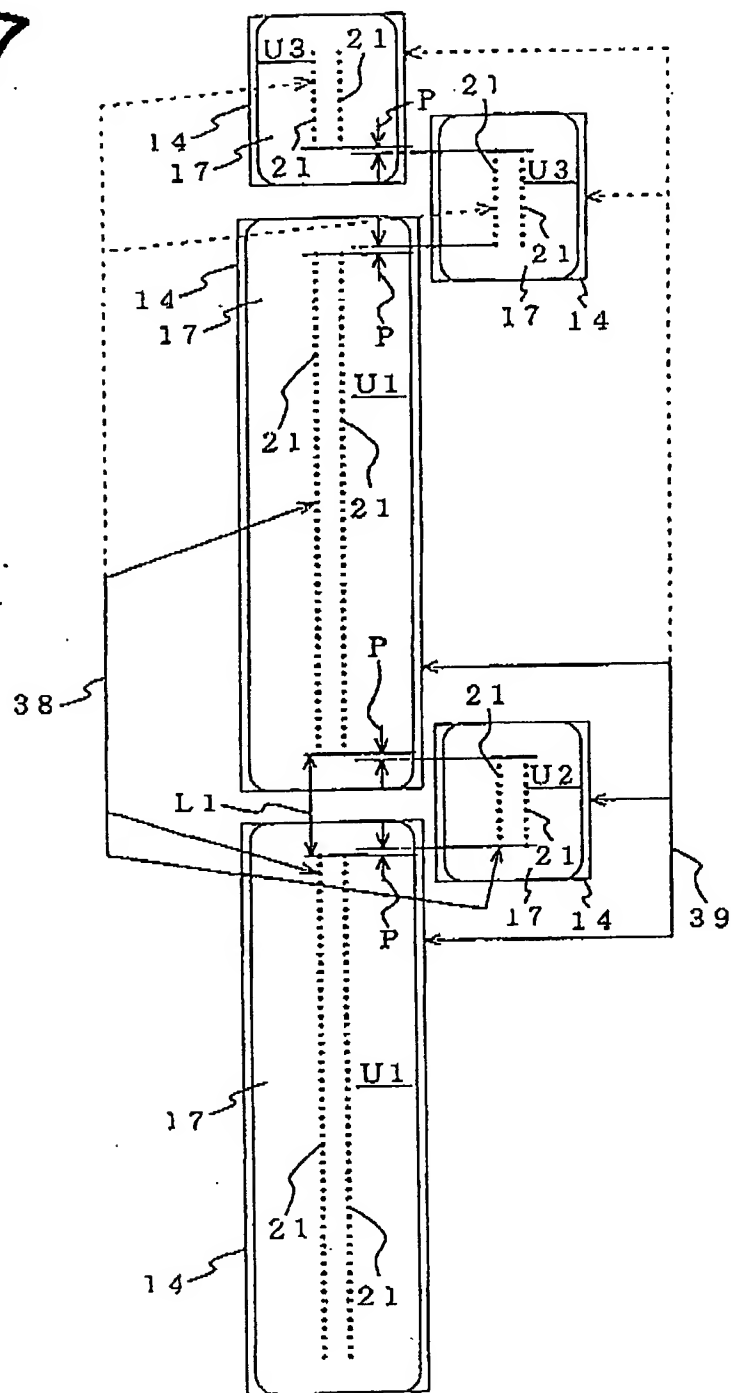


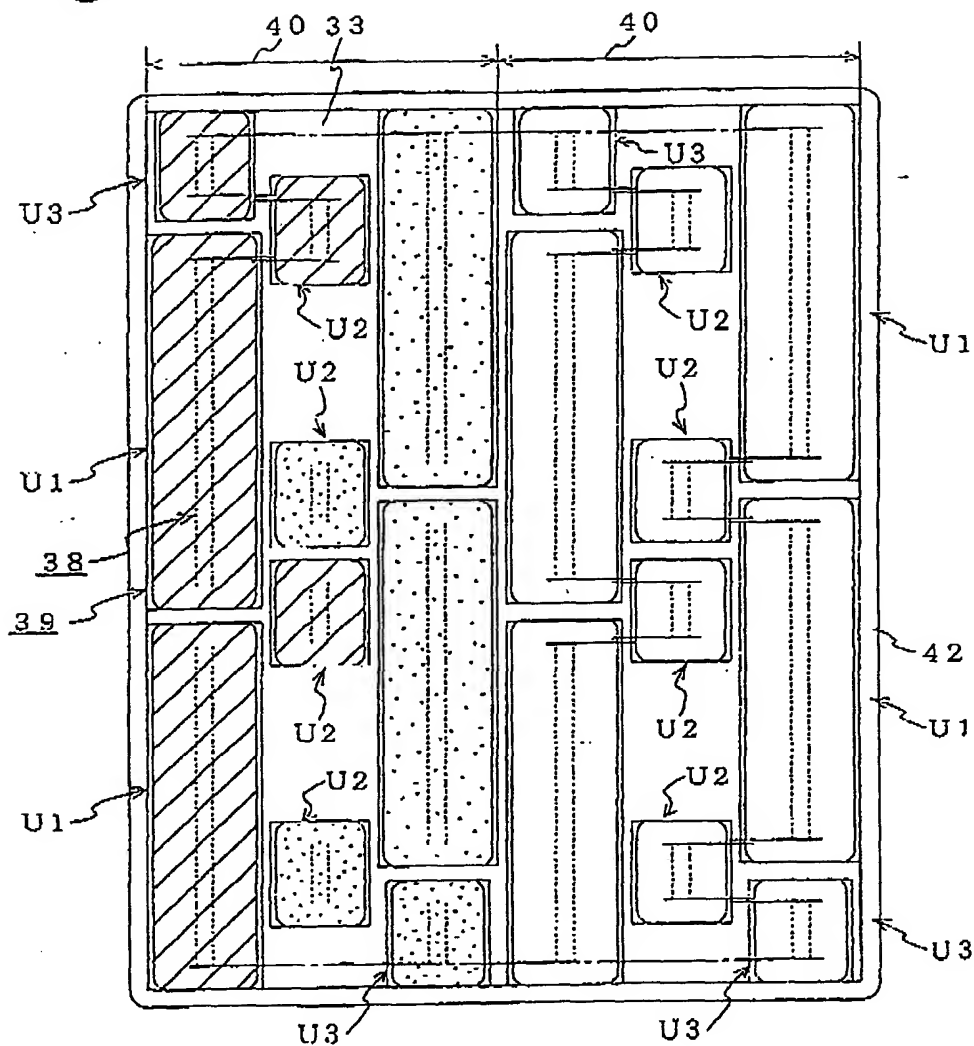
FIG. 6B



~~圖 7~~



~~FIG. 8~~  
FIG. 8





~~図 9~~  
FIG. 9

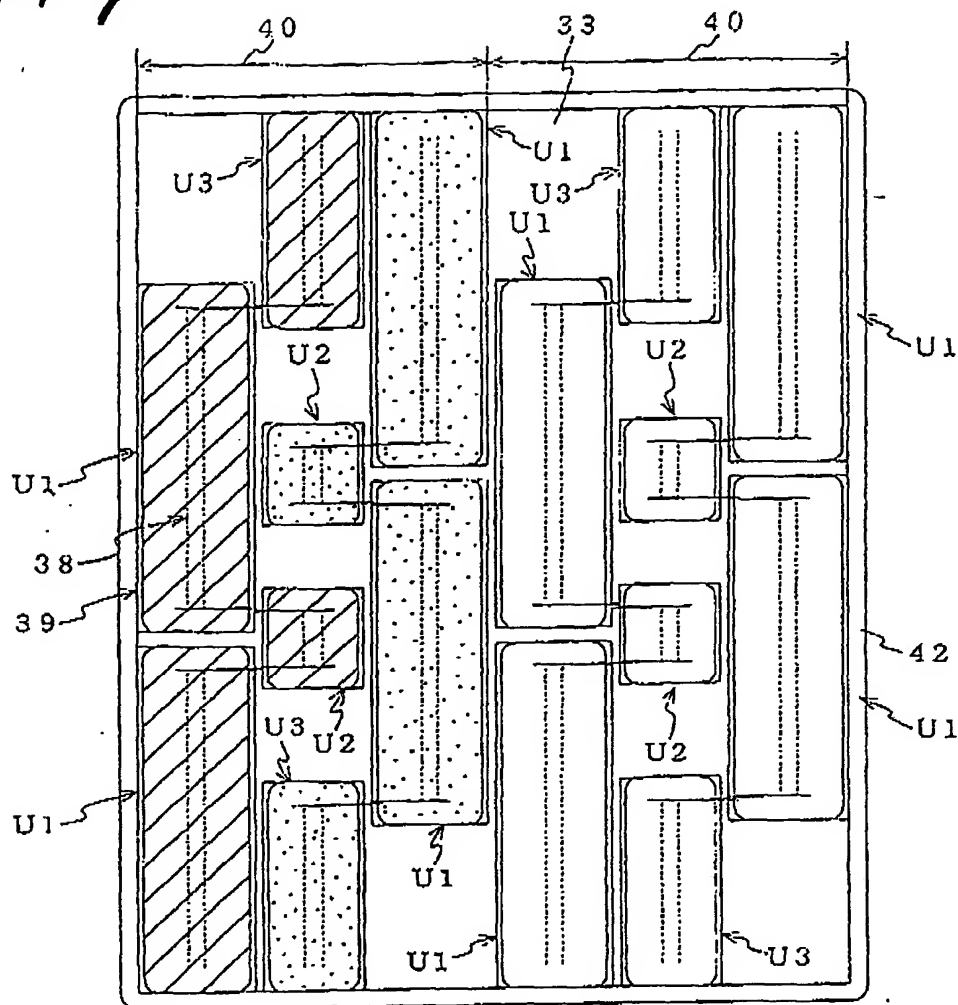
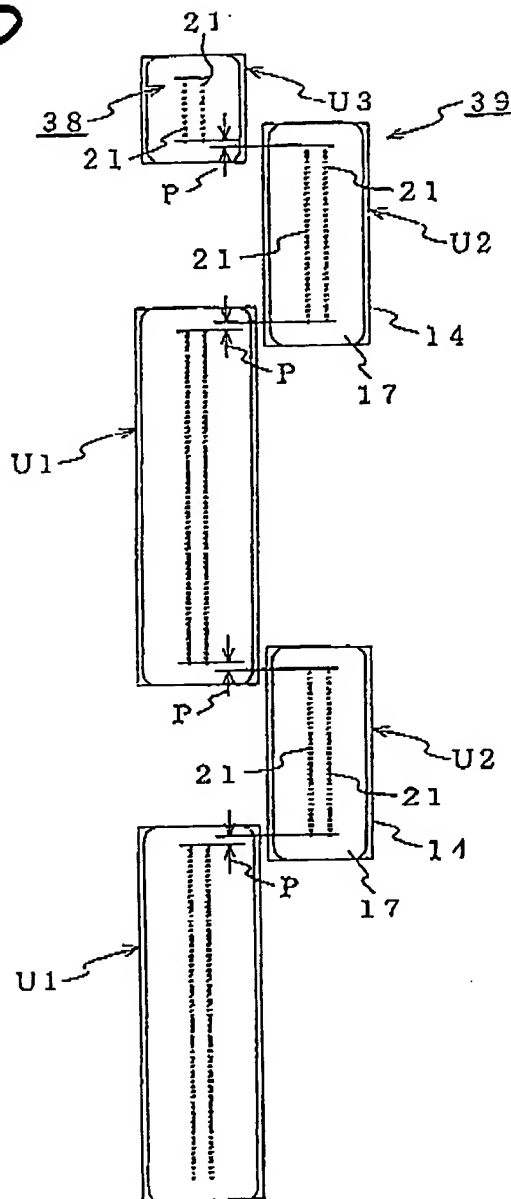
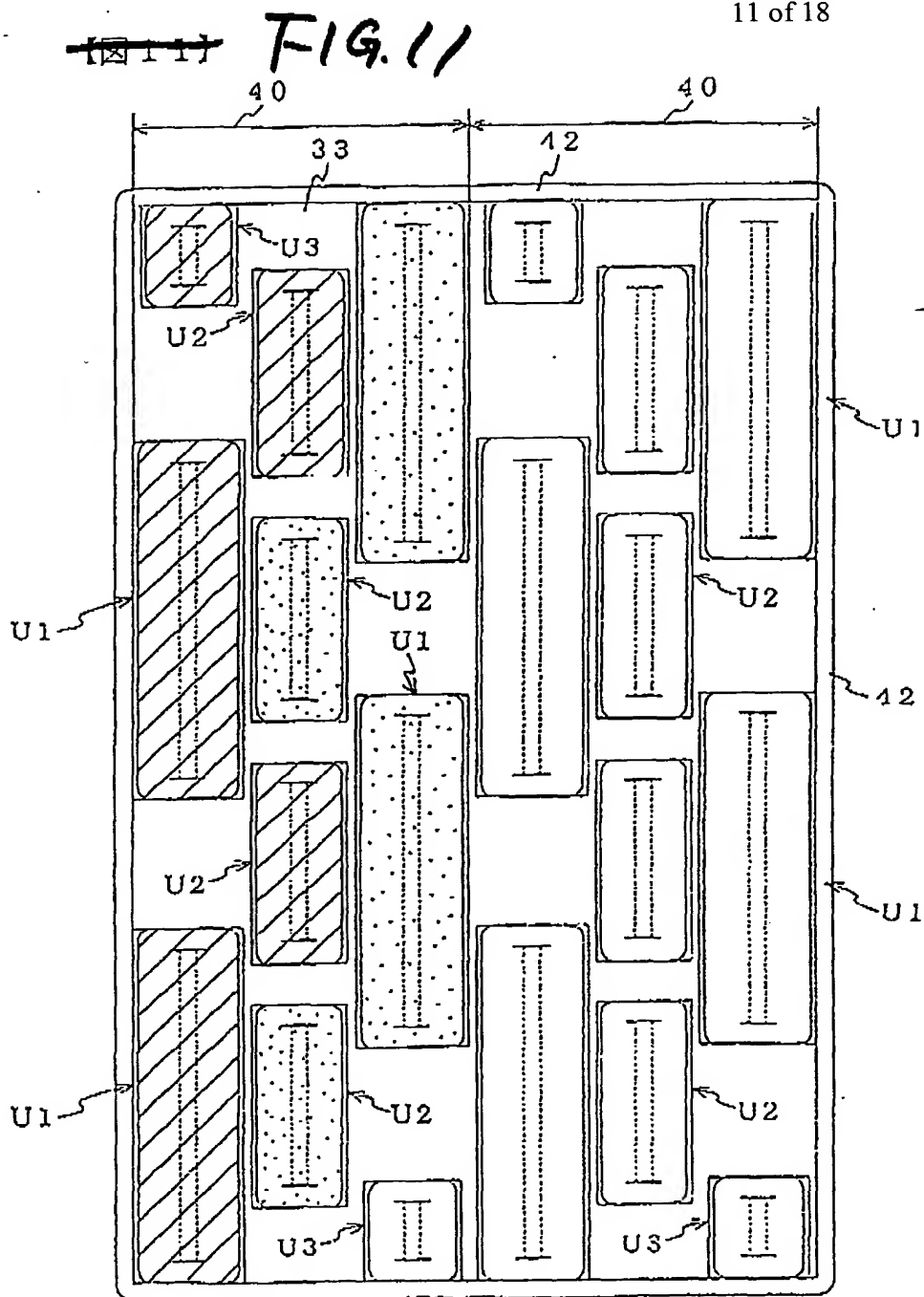


FIG. 10





~~FIG. 12~~ FIG. 12

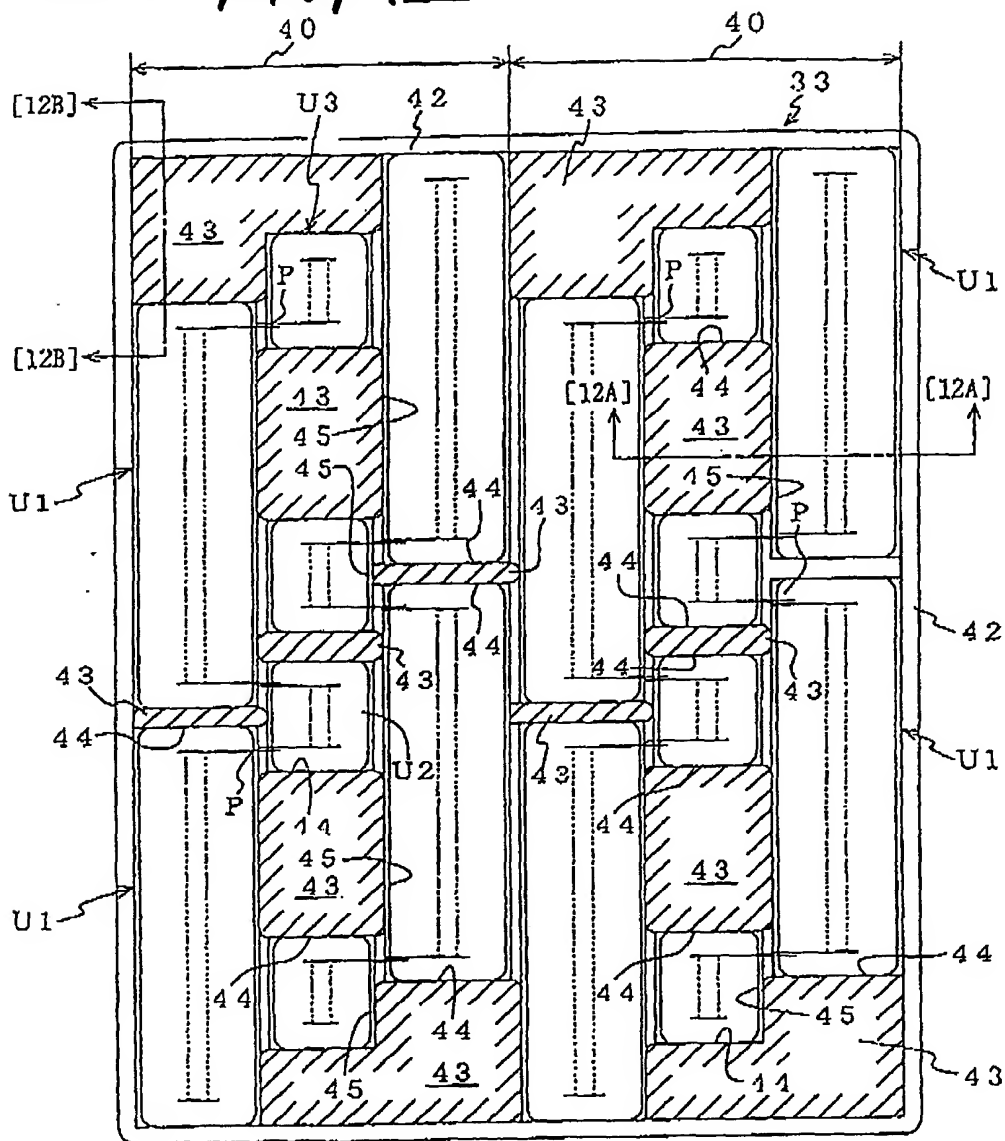
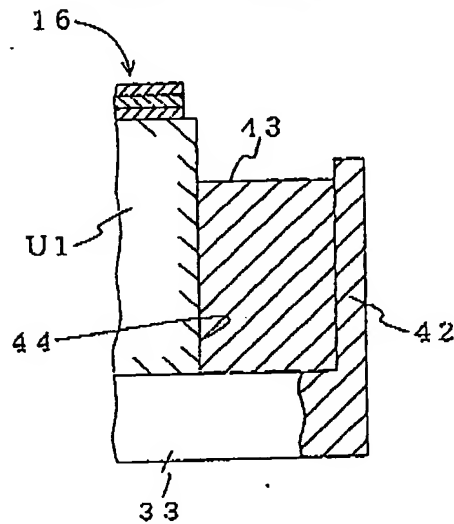
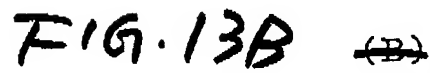
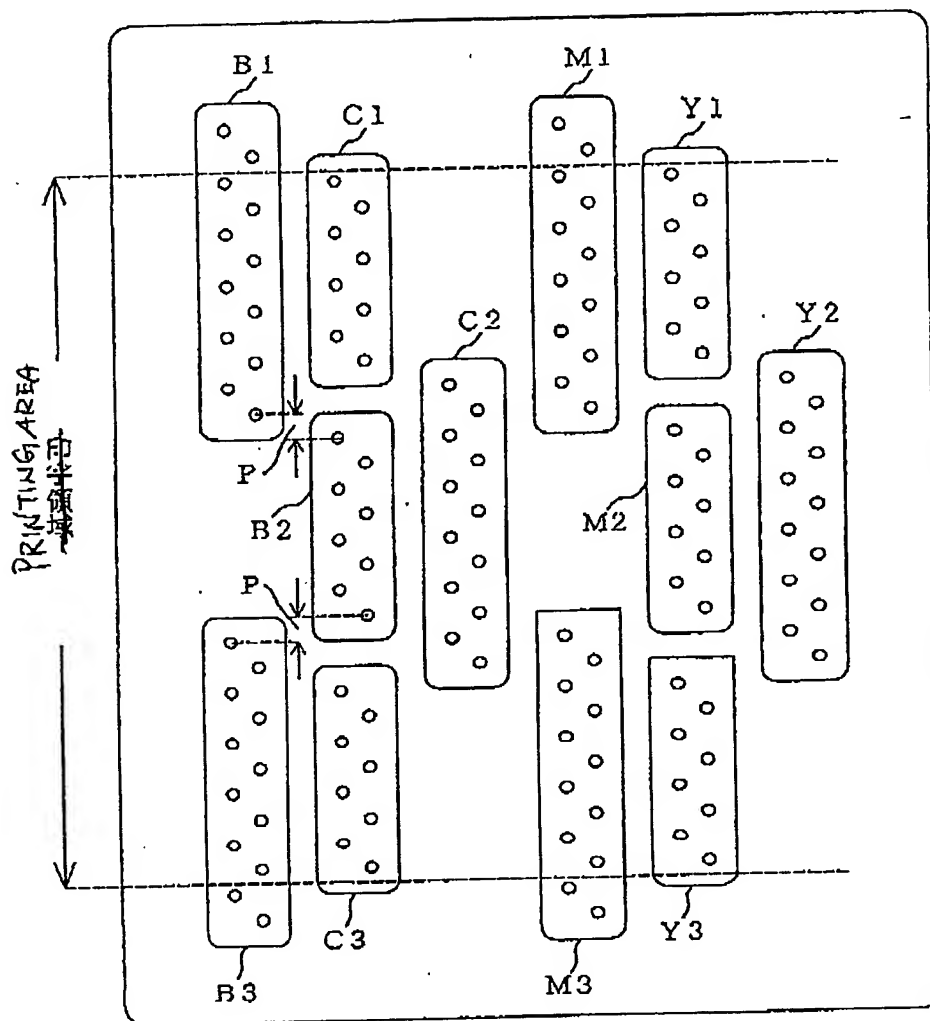


FIG. 13A



~~【図14】~~

FIG. 14



~~図15~~

FIG. 15A

(A)

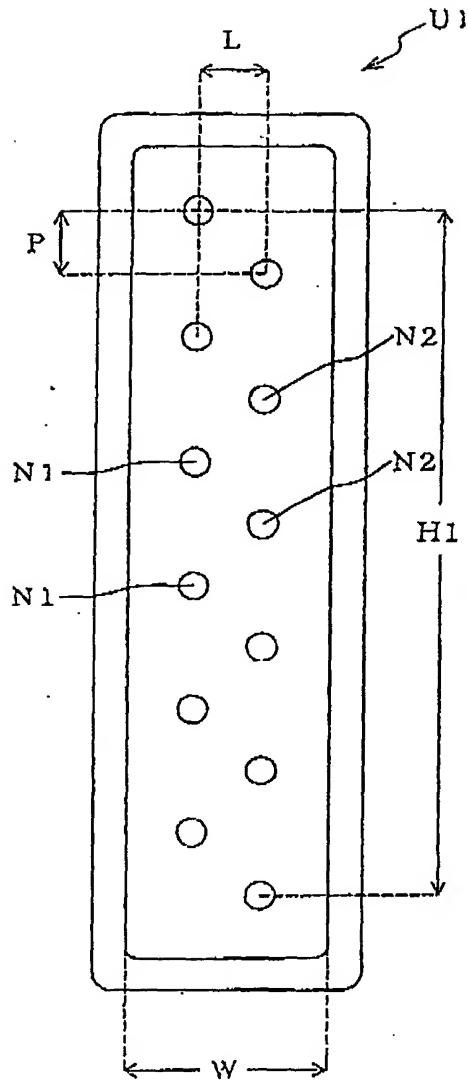
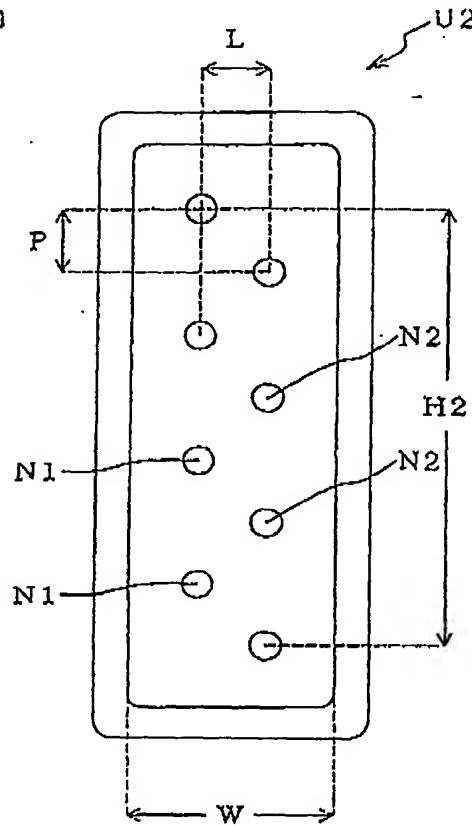


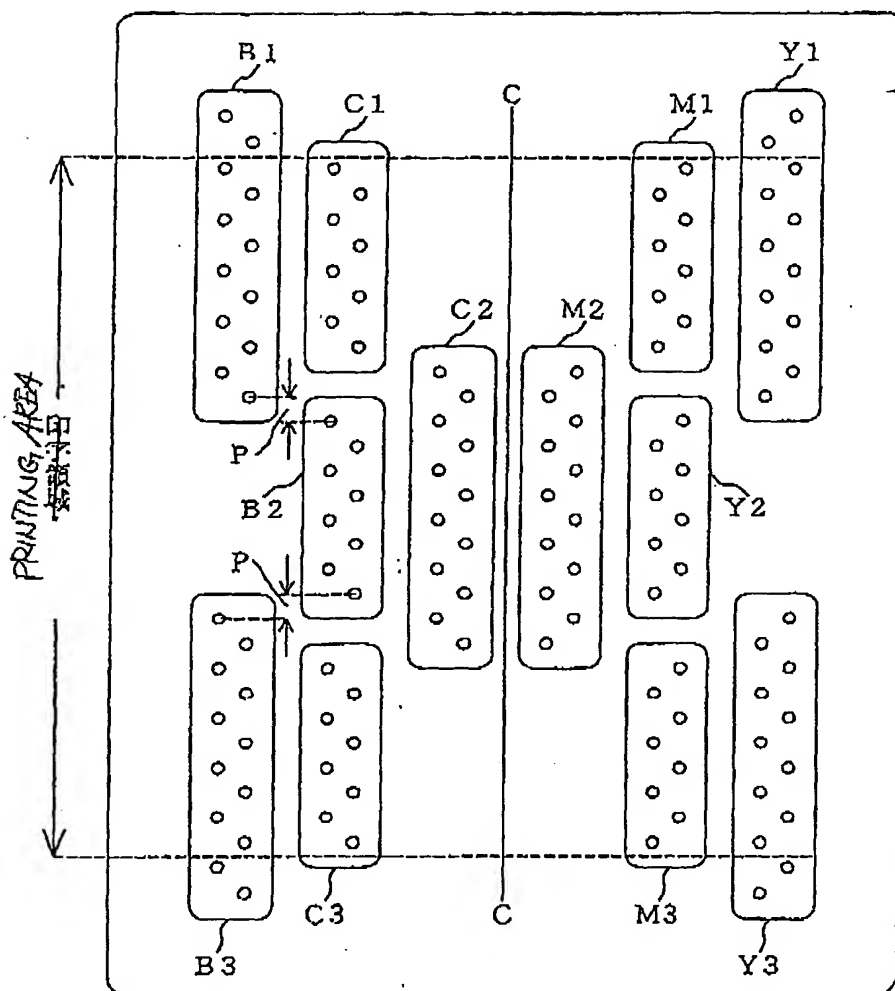
FIG. 15B

(B)



~~【図16】~~

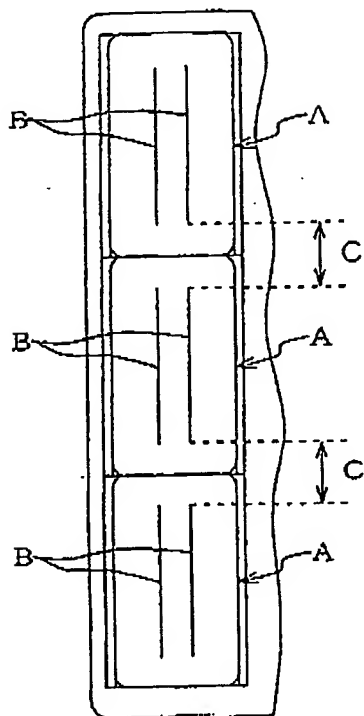
FIG. 16



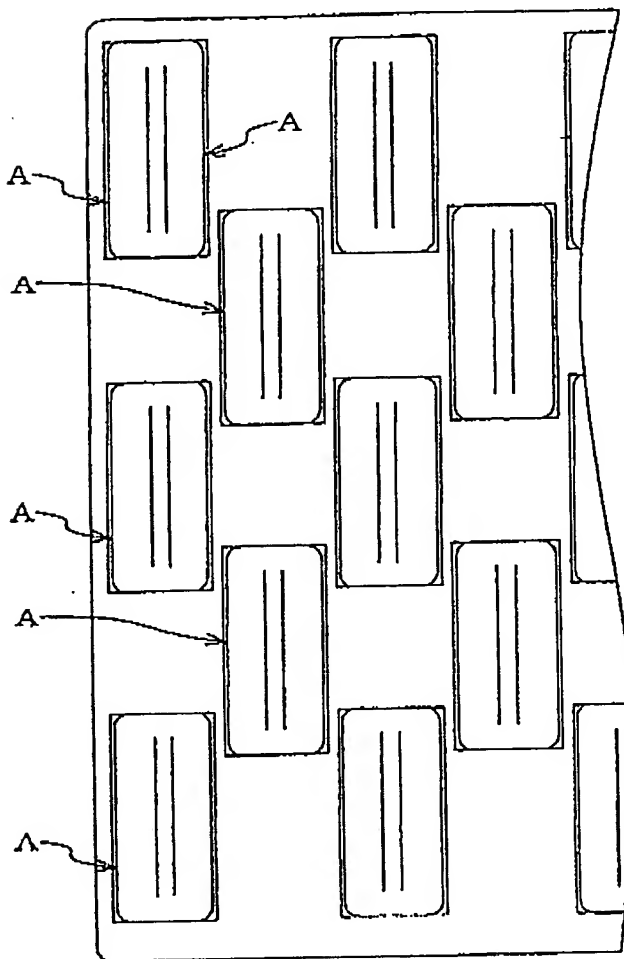


~~【図17】~~

~~FIG. 17A~~ (A)



~~FIG. 17B~~ (B)



This exploded perspective view illustrates the assembly of the semiconductor device. The components are labeled as follows: 17 is the base substrate; 20 and 21 are conductive pads on the base; 22 is a conductive layer; 23 and 25 are conductive pads; 19A is a conductive layer; 19 is a conductive layer; 26 is a conductive layer; 31 is a conductive layer; 31D is a conductive layer; 15 is a conductive layer; 14 is a conductive layer; 30 is a conductive layer; 35 is a conductive layer; 29 is a conductive layer; 32 is a conductive layer; 34 is a conductive layer; 36 is a conductive layer; 37 is a conductive layer; 33 is a conductive layer.